APPARATUS AND PROCESS FOR IMPROVED DIE ADHESION TO ORGANIC CHIP CARRIERS

ABSTRACT

A semiconductor package and method for preparing same to obtain improved die adhesion to organic chip carriers has been developed. A copper die bond pad (1) is coated with a passivation material and attached to an organic card (2) with the same passivation material. A semiconductor die may be adhered to the coated die bond pad (1) with either the same passivation material or a common die bond adhesive. Alternatively, the passivation material is coated only on the portion of the die bond pad (1) where the die is attached, and common die bond adhesive attaches the die bond pad (1) to the organic card (2).

Fig. 1